

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
25 August 2005 (25.08.2005)

PCT

(10) International Publication Number  
**WO 2005/076871 A2**

(51) International Patent Classification: Not classified

(21) International Application Number:  
PCT/US2005/003264

(22) International Filing Date: 3 February 2005 (03.02.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
60/542,058 4 February 2004 (04.02.2004) US  
60/566,699 30 April 2004 (30.04.2004) US

(71) Applicant and  
(72) Inventor: LOMBARDI, John, L. [US/US]; 831 N.  
Camino Miramonte, Tucson, Arizona 85716 (US).

(74) Agent: REGELMAN, Dale F.; Law Office of Dale F.  
Regelman, P.C., 4231 S. Fremont Avenue, Tucson, Arizona  
85714 (US).

(81) Designated States (unless otherwise indicated, for every  
kind of national protection available): AE, AG, AL, AM,

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,  
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,  
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,  
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,  
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,  
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,  
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,  
ZW.

(84) Designated States (unless otherwise indicated, for every  
kind of regional protection available): ARIPO (BW, GH,  
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,  
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),  
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,  
FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,  
SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,  
GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

— without international search report and to be republished  
upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guid-  
ance Notes on Codes and Abbreviations" appearing at the begin-  
ning of each regular issue of the PCT Gazette.

(54) Title: LAPPING COMPOSITION AND METHOD USING SAME

(57) Abstract: Lapping compositions are disclosed which comprise a fluid useful during a process to shape the surface of a substrate, where that process includes contacting a target surface of the substrate with one or more abrasives while also contacting that target surface with the lapping composition.



WO 2005/076871 A2